

EMERGENCY PHONE 1-800-255-3924
TECHNICAL DATA SHEETS
MP 54125

Description:

MP 54125 is a two part, unfilled epoxy adhesive designed for bonding metals and plastics. It cures at room temperature to a tough, semi-rigid material. It has good wetting to most surfaces. This product gives very good vibration and impact resistance with high peel and shear strengths. It gives good resistance to water, salt spray, inorganic acids and bases and most organic solvents.

It was especially formulated to a 1A:1B volume mix ratio for use in side-by-side dispensing cartridges and meter/mix and dispense equipment. **MP 54125** Clear will reach full cure at room temperature within 24 –48 hours. Cure time can be accelerated by the application of heat. Times and temperatures from 2 hours at 65°C to 20 minutes at 100°C are typical for most applications. Time to heat substrate must be taken into account. Cooler temperatures will also extend work time and increase cure times.

Typical Properties:

All properties given are at 25°C unless otherwise noted.

Color	Clear	
Viscosity	Part A	7,000 cps
	Part B	5,000 cps
	Mixed	6,000 cps
Specific Gravity	Part A	1.12
	Part B	0.98
	Mixed	1.05
Pot Life	20 – 30 minutes	
Mass	50 grams	
Temperature Range **	-40 to 150°C	
Hardness	70	
Method	Shore -D	
Dielectric Constant (25°C, 1 KHz)	6.3 *	
Dielectric Strength	680 v/mil *	
Volume Resistivity	1.0 x 10 ¹¹ ohm-cm *	

INSTRUCTIONS:

1. Bring both components to room temperature prior to mixing.
2. If used in bulk, weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on surface of casting. If product is used in a side-by-side cartridge, attach a new static mixer with each cartridge, pre-bleed the first 3 inches of dispensed material or until a uniform color is obtained. Maintain adequate velocity during dispensing to ensure complete mixing.
3. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
4. Clean up uncured resin with suitable organic solvent such as MEK, acetone or other organic solvent.

MIX RATIO:

1.14 A:1 B by weight or 1 A:1 B by volume.

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

** Temperature Rating is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.

Engineering Excellence

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